

Title (en)

INTERPOSER AND METHOD FOR PRODUCING HOLES IN AN INTERPOSER

Title (de)

INTERPOSER UND VERFAHREN ZUR HERSTELLUNG VON LÖCHERN IN EINEM INTERPOSER

Title (fr)

INTERPOSEUR ET PROCÉDÉ POUR RÉALISER DES TROUS DANS UN INTERPOSEUR

Publication

EP 2589072 A2 20130508 (DE)

Application

EP 11730223 A 20110704

Priority

- DE 102010025966 A 20100702
- EP 2011003300 W 20110704

Abstract (en)

[origin: WO2012000685A2] Interposer for electrical connection between a CPU chip and a circuit board. A board-shaped base substrate (1) composed of glass has a coefficient of thermal expansion in the range of between $3.1 \cdot 10^{-6}$ and $3.4 \cdot 10^{-6}$ and holes (12) in a number that is in the range of between 10 and 10,000 cm⁻². There are holes (12) having diameters which can be in the range of between 20 µm and 200 µm. Conductor tracks (13) run on one board side, said conductor tracks in each case extending right into the holes (12) and through the latter to the other board side in order to form connection points for the chip.

IPC 8 full level

H01L 21/48 (2006.01); **H01L 23/15** (2006.01); **H01L 23/498** (2006.01)

CPC (source: EP KR US)

B23K 26/0093 (2013.01 - EP US); **B23K 26/0622** (2015.10 - EP US); **B23K 26/126** (2013.01 - EP US); **B23K 26/14** (2013.01 - EP US); **B23K 26/38** (2013.01 - US); **B23K 26/382** (2015.10 - EP US); **B23K 26/384** (2015.10 - EP US); **B23K 26/40** (2013.01 - EP US); **H01L 21/486** (2013.01 - EP US); **H01L 23/15** (2013.01 - EP US); **H01L 23/48** (2013.01 - KR); **H01L 23/498** (2013.01 - KR); **H01L 23/49827** (2013.01 - EP US); **H05K 1/0306** (2013.01 - EP US); **H05K 1/115** (2013.01 - US); **H05K 3/0029** (2013.01 - EP US); **B23K 2101/40** (2018.07 - EP US); **B23K 2103/42** (2018.07 - EP US); **B23K 2103/50** (2018.07 - EP US); **H01L 2924/0002** (2013.01 - EP US); **H05K 3/0017** (2013.01 - EP US); **H05K 2201/10378** (2013.01 - EP US); **H05K 2203/087** (2013.01 - EP US)

Citation (search report)

See references of WO 2012000685A2

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

DE 102010025966 A1 20120105; **DE 102010025966 B4 20120308**; CN 102971838 A 20130313; CN 102971838 B 20151125; EP 2589072 A2 20130508; JP 2013531380 A 20130801; JP 2016195270 A 20161117; JP 2019041133 A 20190314; JP 6208010 B2 20171004; JP 6841607 B2 20210310; KR 101598260 B1 20160226; KR 101726982 B1 20170413; KR 20130040224 A 20130423; KR 20160013259 A 20160203; US 11744015 B2 20230829; US 2013210245 A1 20130815; US 2020045817 A1 20200206; WO 2012000685 A2 20120105; WO 2012000685 A3 20120308

DOCDB simple family (application)

DE 102010025966 A 20100702; CN 201180032797 A 20110704; EP 11730223 A 20110704; EP 2011003300 W 20110704; JP 2013517092 A 20110704; JP 2016132647 A 20160704; JP 2018235537 A 20181217; KR 20137001035 A 20110704; KR 20167001285 A 20110704; US 201113807386 A 20110704; US 201916600191 A 20191011